	CONNECTING CS INDUSTRIES® International and Part	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	ion of the s encompasse	ubstances es all lower	within the manufac level materials for	turer listed which the	l item. Note: manufacture	if the item is an as r has engineering	ssembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					erials and	als and Mfg Information				
Supplie	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority				Respo	Response Date*				
onsemi											2025-0	2025-06-25			
Contact N	lame	Title - Contact]	Phone - Contact*				Email	Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email	Email - Representative*			
Product-	Env-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item Number Mfr Item Name FSB50550A SPM5 V2 INV 5		Number Mfr Item Name				Effective Date	e Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
			SPM5 V2 INV 50	500V 1.40hm		2025-06-25		(СРА		3355.2	mg	Each		
/Ianufa	cturing Proccess Informat	tion											I		
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		-STD-020 MS	L Rating	Peak Process Body Temperat		emperatur	e Max Time at Pe	ak Temper	ature Num	ber of Reflow Cyc	cles	
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		С	30	seco	onds 3				
omments	5														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	ition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ry (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl BP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	24.0	mg	Supplier	Silicon (Si)	7440-21-3		24	mg
Die Attach	6.0	mg	Supplier	Silver (Ag)	7440-22-4		4.56	mg
			Supplier	Phenolic Resin-2	54208-63-8		1.44	mg
Die Attach Solder	4.8	mg	Supplier	Silver (Ag)	7440-22-4		0.12	mg
			А	Lead (Pb)	7439-92-1	7a	4.44	mg
			Supplier	Tin (Sn)	7440-31-5		0.24	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1890.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		132.3	mg
			Supplier	Carbon Black (C)	1333-86-4		18.9	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		661.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		132.3	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		945	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	4.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			Supplier	Copper (Cu)	7440-50-8		3.92	mg